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PIC24FJ128GA010 FAMILY

64/80/100-Pin, General Purpose, 16-Bit Flash Microcontrollers

High-Performance CPU:

- Modified Harvard Architecture
- Up to 16 MIPS Operation @ 32 MHz
- 8 MHz Internal Oscillator with 4x PLL Option and Multiple Divide Options
- 17-Bit x 17-Bit Single-Cycle Hardware Multiplier
- 32-Bit by 16-Bit Hardware Divider
- 16 x 16-Bit Working Register Array
- C Compiler Optimized Instruction Set Architecture:
  - 76 base instructions
  - Flexible addressing modes
- Two Address Generation Units for Separate Read and Write Addressing of Data Memory

Special Microcontroller Features:

- Operating Voltage Range of 2.0V to 3.6V
- Flash Program Memory:
  - 1000 erase/write cycles
  - 20-year data retention minimum
- Self-Reprogrammable under Software Control
- Selectable Power Management modes:
  - Sleep, Idle and Alternate Clock modes
- Fail-Safe Clock Monitor Operation:
  - Detects clock failure and switches to on-chip, low-power RC oscillator
- On-Chip 2.5V Regulator
- JTAG Boundary Scan and Programming Support
- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Flexible Watchdog Timer (WDT) with On-Chip, Low-Power RC Oscillator for Reliable Operation
- In-Circuit Serial Programming™ (ICSP™) and In-Circuit Emulation (ICE) via 2 Pins

Analog Features:

- 10-Bit, Up to 16-Channel Analog-to-Digital Converter
  - 500 ksps conversion rate
  - Conversion available during Sleep and Idle
- Dual Analog Comparators with Programmable Input/Output Configuration

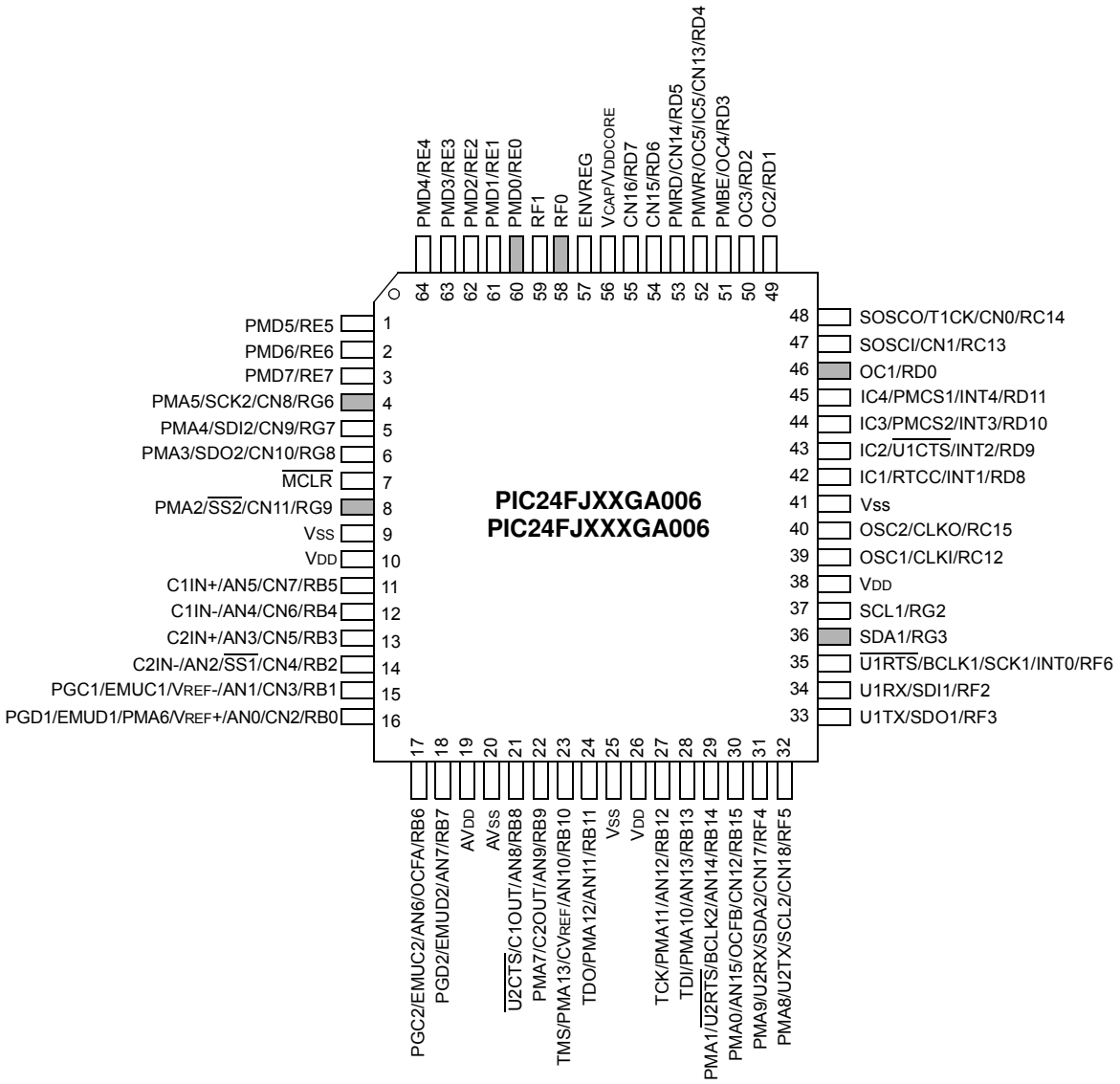
Peripheral Features:

- Two 3-Wire/4-Wire SPI modules, Supporting 4 Frame modes with 8-Level FIFO Buffer
- Two I^2C™ modules Support Multi-Master/Slave mode and 7-Bit/10-Bit Addressing
- Two UART modules:
  - Supports RS-232, RS-485 and LIN/J2602
  - On-chip hardware encoder/decoder for IrDA®
  - Auto-wake-up on Start bit
  - Auto-Baud Detect
  - 4-level FIFO buffer
- Parallel Master Slave Port (PMP/PSP):
  - Supports 8-bit or 16-bit data
  - Supports 16 address lines
- Hardware Real-Time Clock/Calendar (RTCC):
  - Provides clock, calendar and alarm functions
- Programmable Cyclic Redundancy Check (CRC)
  - User-programmable polynomial
  - 8/16-level FIFO buffer
- Five 16-Bit Timers/Counters with Programmable Prescaler
- Five 16-Bit Capture Inputs
- Five 16-Bit Compare/PWM Outputs
- High-Current Sink/Source (18 mA/18 mA) on All I/O Pins
- Configurable, Open-Drain Output on Digital I/O Pins
- Up to 5 External Interrupt Sources
- 5.5V Tolerant Input (digital pins only)

Device	Pins	Program Memory (Bytes)	SRAM (Bytes)	Timers 16-Bit	Capture Input	Compare/ PWM Output	UART	SPI	I^2C™	10-Bit A/D (ch)	Comparators	PMP/PSP	JTAG
PIC24FJ64GA006	64	64K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ96GA006	64	96K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ128GA006	64	128K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ64GA008	80	64K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ96GA008	80	96K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ128GA008	80	128K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ64GA010	100	64K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ96GA010	100	96K	8K	5	5	5	2	2	2	16	2	Y	Y
PIC24FJ128GA010	100	128K	8K	5	5	5	2	2	2	16	2	Y	Y

Pin Diagrams

64-Pin TQFP/QFN(1)

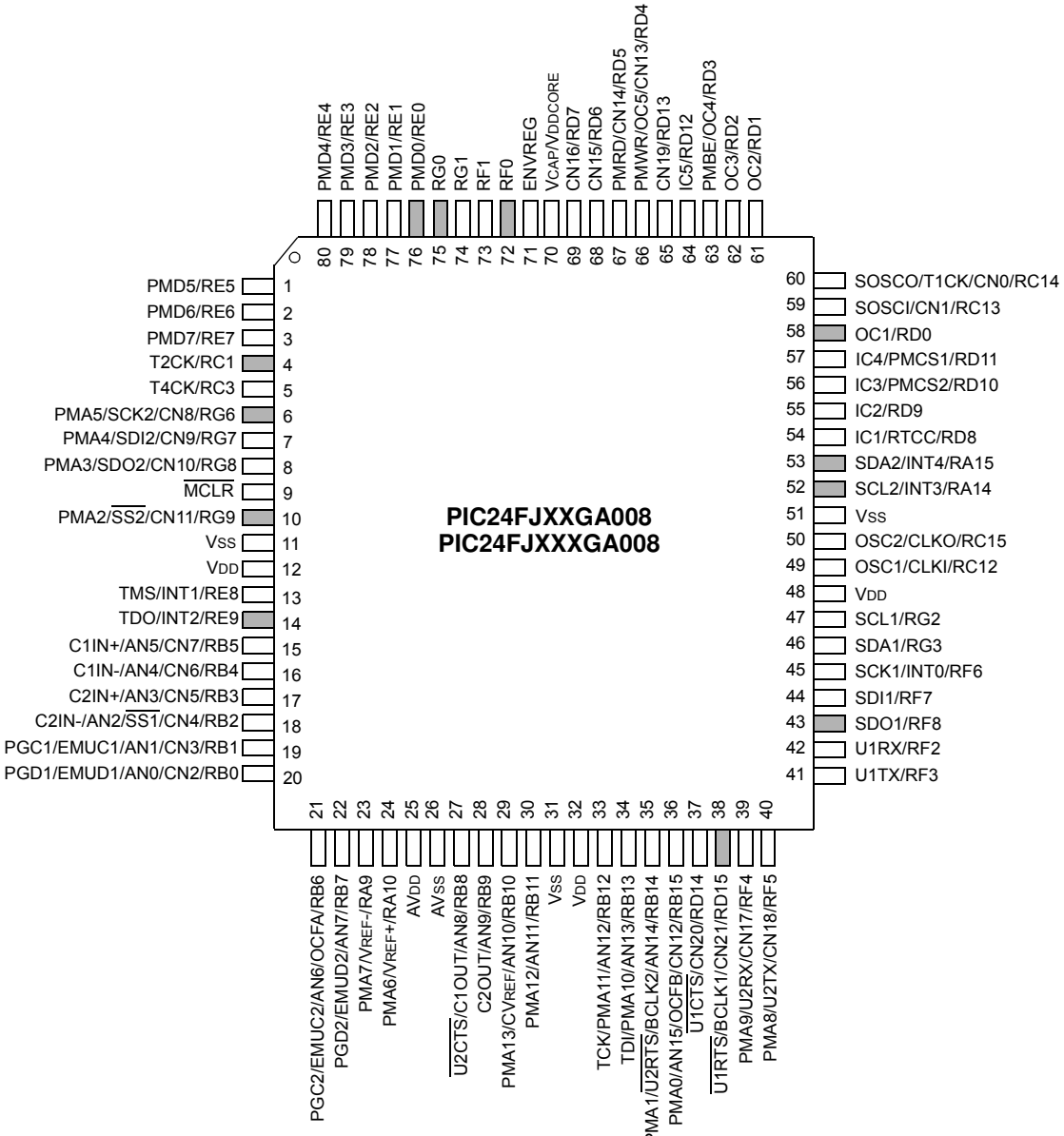


Legend: Shaded pins indicate pins that are tolerant to up to +5.5 VDC.

Note 1: Bottom pad of QFN package must be connected to VSS.

Pin Diagrams (Continued)

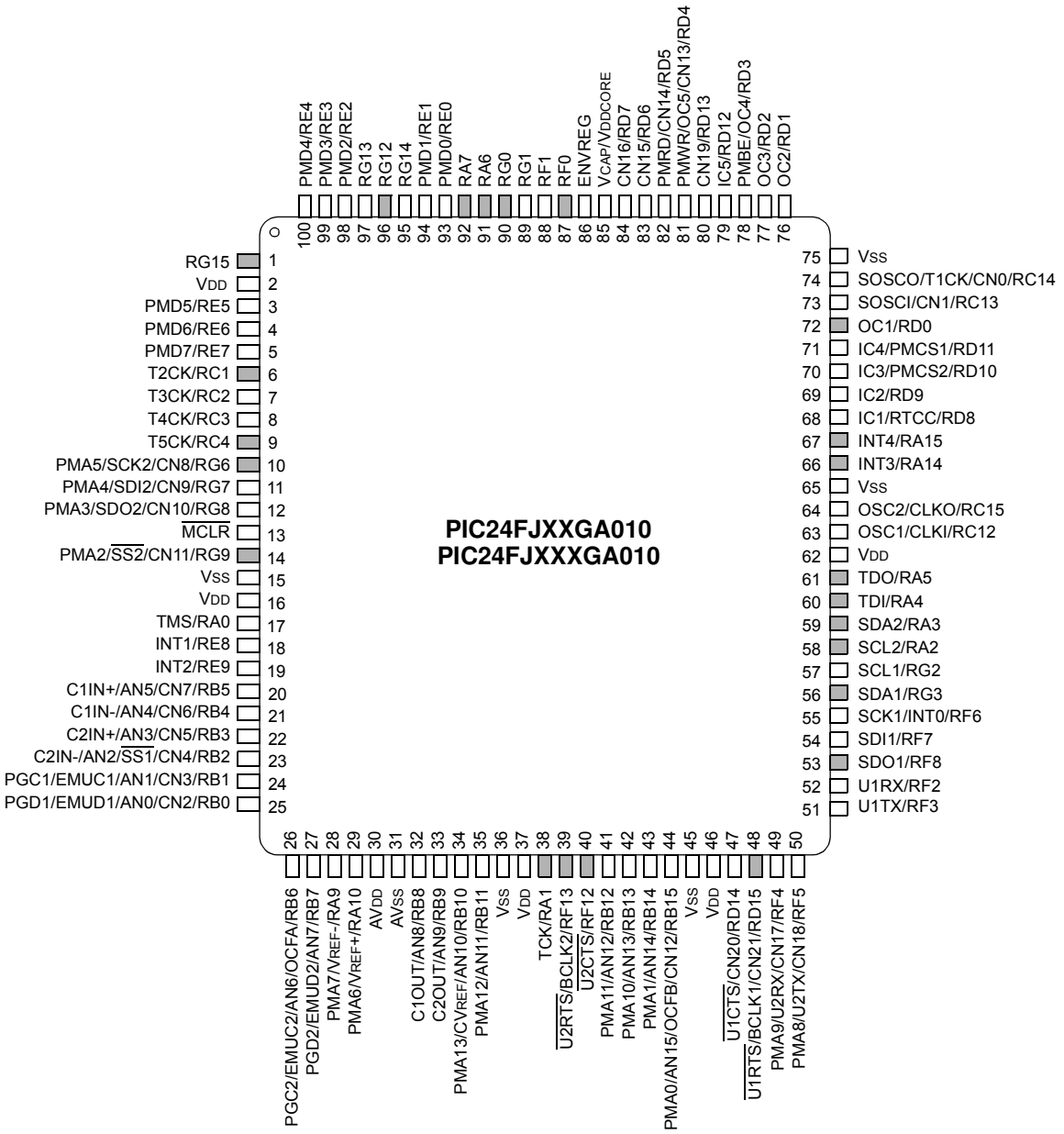
80-Pin TQFP



Legend: Shaded pins indicate pins that are tolerant to up to +5.5 VDC.

Pin Diagrams (Continued))

100-Pin TQFP



Legend: Shaded pins indicate pins that are tolerant to up to +5.5 VDC.

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1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC24FJ64GA006
- PIC24FJ64GA008
- PIC24FJ64GA010
- PIC24FJ96GA006
- PIC24FJ96GA008
- PIC24FJ96GA010
- PIC24FJ128GA006
- PIC24FJ128GA008
- PIC24FJ128GA010

This family introduces a new line of Microchip devices: a 16-bit microcontroller family with a broad peripheral feature set and enhanced computational performance. The PIC24FJ128GA010 family offers a new migration option for those high-performance applications which may be outgrowing their 8-bit platforms, but don't require the numerical processing power of a digital signal processor.

1.1 Core Features

1.1.1 16-BIT ARCHITECTURE

Central to all PIC24F devices is the 16-bit modified Harvard architecture, first introduced with Microchip's dsPIC® digital signal controllers. The PIC24F CPU core offers a wide range of enhancements, such as:

- 16-bit data and 24-bit address paths, with the ability to move information between data and memory spaces
- Linear addressing of up to 8 Mbytes (program space) and 64 Kbytes (data)
- A 16-element working register array with built-in software stack support
- A 17 x 17 hardware multiplier with support for integer math
- Hardware support for 32 by 16-bit division
- An instruction set that supports multiple addressing modes and is optimized for high-level languages such as 'C'
- Operational performance up to 16 MIPS

1.1.2 POWER-SAVING TECHNOLOGY

All of the devices in the PIC24FJ128GA010 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **On-the-Fly Clock Switching:** The device clock can be changed under software control to the Timer1 source or the internal low-power RC oscillator during operation, allowing the user to incorporate power-saving ideas into their software designs.
- **Doze Mode Operation:** When timing-sensitive applications, such as serial communications, require the uninterrupted operation of peripherals, the CPU clock speed can be selectively reduced, allowing incremental power savings without missing a beat.
- **Instruction-Based Power-Saving Modes:** The microcontroller can suspend all operations, or selectively shut down its core while leaving its peripherals active, with a single instruction in software.

1.1.3 OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC24FJ128GA010 family offer five different oscillator options, allowing users a range of choices in developing application hardware. These include:

- Two Crystal modes using crystals or ceramic resonators.
- Two External Clock modes offering the option of a divide-by-2 clock output.
- A Fast Internal Oscillator (FRC) with a nominal 8 MHz output, which can also be divided under software control to provide clock speeds as low as 31 kHz.
- A Phase Lock Loop (PLL) frequency multiplier, available to the external oscillator modes and the FRC oscillator, which allows clock speeds of up to 32 MHz.
- A separate internal RC oscillator (LPRC) with a fixed, 31 kHz output, which provides a low-power option for timing-insensitive applications.

The internal oscillator block also provides a stable reference source for the Fail-Safe Clock Monitor. This option constantly monitors the main clock source against a reference signal provided by the internal oscillator and enables the controller to switch to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.

1.1.4 EASY MIGRATION

Regardless of the memory size, all devices share the same rich set of peripherals, allowing for a smooth migration path as applications grow and evolve.

The consistent pinout scheme used throughout the entire family also aids in migrating to the next larger device. This is true when moving between devices with the same pin count, or even jumping from 64-pin to 80-pin to 100-pin devices.

The PIC24F family is pin-compatible with devices in the dsPIC33 family, and shares some compatibility with the pinout schema for PIC18 and dsPIC30. This extends the ability of applications to grow from the relatively simple, to the powerful and complex, yet still selecting a Microchip device.

1.2 Other Special Features

- **Communications:** The PIC24FJ128GA010 family incorporates a range of serial communication peripherals to handle a range of application requirements. All devices are equipped with two independent UARTs with built-in IrDA encoder/decoders. There are also two independent SPI modules, and two independent I^2C modules that support both Master and Slave modes of operation.
- **Parallel Master/Enhanced Parallel Slave Port:** One of the general purpose I/O ports can be reconfigured for enhanced parallel data communications. In this mode, the port can be configured for both master and slave operations, and supports 8-bit and 16-bit data transfers with up to 16 external address lines in Master modes.
- **Real-Time Clock/Calendar:** This module implements a full-featured clock and calendar with alarm functions in hardware, freeing up timer resources and program memory space for use of the core application.
- **10-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, as well as faster sampling speeds.

1.3 Details on Individual Family Members

Devices in the PIC24FJ128GA010 family are available in 64-pin, 80-pin and 100-pin packages. The general block diagram for all devices is shown in Figure 1-1.

The devices are differentiated from each other in two ways:

1. Flash program memory (64 Kbytes for PIC24FJ64GA devices, 96 Kbytes for PIC24FJ96GA devices and 128 Kbytes for PIC24FJ128GA devices).
2. Available I/O pins and ports (53 pins on 6 ports for 64-pin devices, 69 pins on 7 ports for 80-pin devices and 84 pins on 7 ports for 100-pin devices). Note also that, since interrupt-on-change inputs are available on every I/O pin for this family of devices, the number of CN inputs also differs between package sizes.

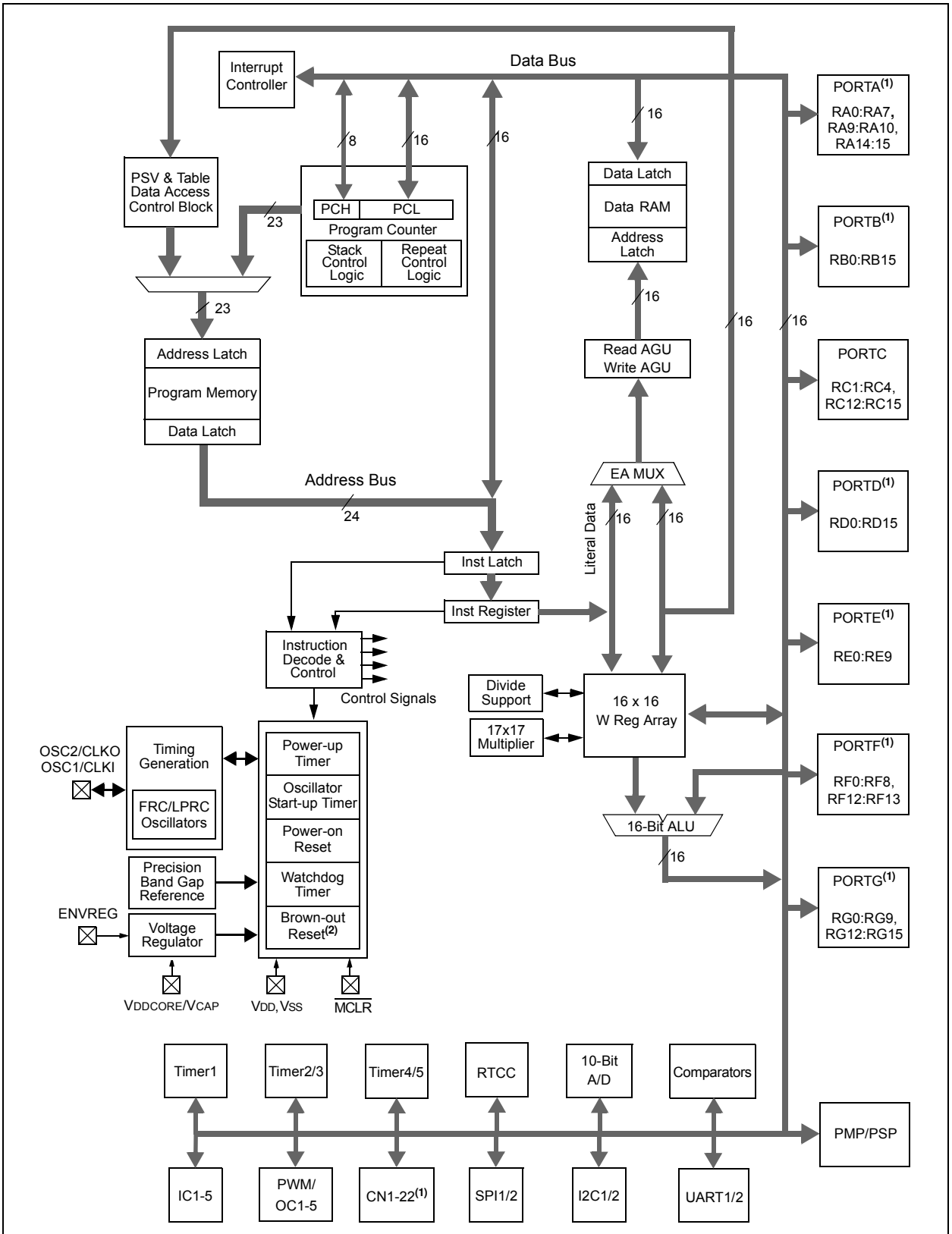
All other features for devices in this family are identical. These are summarized in Table 1-1.

A list of the pin features available on the PIC24FJ128GA010 family devices, sorted by function, is shown in Table 1-2. Note that this table shows the pin location of individual peripheral features and not how they are multiplexed on the same pin. This information is provided in the pinout diagrams in the beginning of the data sheet. Multiplexed features are sorted by the priority given to a feature, with the highest priority peripheral being listed first.

TABLE 1-1: DEVICE FEATURES FOR THE PIC24FJ128GA010 FAMILY

Features	PIC24FJ64GA006	PIC24FJ96GA006	PIC24FJ128GA006	PIC24FJ64GA008	PIC24FJ96GA008	PIC24FJ128GA008	PIC24FJ64GA010	PIC24FJ96GA010	PIC24FJ128GA010
Operating Frequency	DC – 32 MHz								
Program Memory (Bytes)	64K	96K	128K	64K	96K	128K	64K	96K	128K
Program Memory (Instructions)	22,016	32,768	44,032	22,016	32,768	44,032	22,016	32,768	44,032
Data Memory (Bytes)	8192								
Interrupt Sources (Soft Vectors/NMI Traps)	43 (39/4)								
I/O Ports	Ports B, C, D, E, F, G			Ports A, B, C, D, E, F, G			Ports A, B, C, D, E, F, G		
Total I/O Pins	53			69			84		
Timers:									
Total Number (16-bit)	5								
32-Bit (from paired 16-bit timers)	2								
Input Capture Channels	5								
Output Compare/PWM Channels	5								
Input Change Notification Interrupt	19			22					
Serial Communications:									
UART	2								
SPI (3-wire/4-wire)	2								
I^2C™	2								
Parallel Communications (PMP/PSP)	Yes								
JTAG Boundary Scan	Yes								
10-Bit Analog-to-Digital Module (input channels)	16								
Analog Comparators	2								
Resets (and Delays)	POR, BOR, RESET Instruction, $\overline{MCLR}$, WDT, Illegal Opcode, Configuration Word Mismatch, REPEAT Instruction, Hardware Traps (PWRT, OST, PLL Lock)								
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations								
Packages	64-Pin TQFP/QFN			80-Pin TQFP			100-Pin TQFP		

FIGURE 1-1: PIC24FJ128GA010 FAMILY GENERAL BLOCK DIAGRAM



Note 1: Not all pins or features are implemented on all device pinout configurations. See Table 1-2 for I/O port pin descriptions.

2: BOR functionality is provided when the on-board voltage regulator is enabled.

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
AN0	16	20	25	I	ANA	A/D Analog Inputs.
AN1	15	19	24	I	ANA	
AN2	14	18	23	I	ANA	
AN3	13	17	22	I	ANA	
AN4	12	16	21	I	ANA	
AN5	11	15	20	I	ANA	
AN6	17	21	26	I	ANA	
AN7	18	22	27	I	ANA	
AN8	21	27	32	I	ANA	
AN9	22	28	33	I	ANA	
AN10	23	29	34	I	ANA	
AN11	24	30	35	I	ANA	
AN12	27	33	41	I	ANA	
AN13	28	34	42	I	ANA	
AN14	29	35	43	I	ANA	
AN15	30	36	44	I	ANA	
AVDD	19	25	30	P	—	Positive Supply for Analog Modules.
AVSS	20	26	31	P	—	Ground Reference for Analog Modules.
BCLK1	35	38	48	O	—	UART1 IrDA® Baud Clock.
BCLK2	29	35	39	O	—	UART2 IrDA® Baud Clock.
C1IN-	12	16	21	I	ANA	Comparator 1 Negative Input.
C1IN+	11	15	20	I	ANA	Comparator 1 Positive Input.
C1OUT	21	27	32	O	—	Comparator 1 Output.
C2IN-	14	18	23	I	ANA	Comparator 2 Negative Input.
C2IN+	13	17	22	I	ANA	Comparator 2 Positive Input.
C2OUT	22	28	33	O	—	Comparator 2 Output.
CLKI	39	49	63	I	ANA	Main Clock Input Connection.
CLKO	40	50	64	O	—	System Clock Output.
CN0	48	60	74	I	ST	Interrupt-on-Change Inputs.
CN1	47	59	73	I	ST	
CN2	16	20	25	I	ST	
CN3	15	19	24	I	ST	
CN4	14	18	23	I	ST	
CN5	13	17	22	I	ST	
CN6	12	16	21	I	ST	
CN7	11	15	20	I	ST	
CN8	4	6	10	I	ST	
CN9	5	7	11	I	ST	
CN10	6	8	12	I	ST	
CN11	8	10	14	I	ST	
CN12	30	36	44	I	ST	
CN13	52	66	81	I	ST	
CN14	53	67	82	I	ST	
CN15	54	68	83	I	ST	
CN16	55	69	84	I	ST	
CN17	31	39	49	I	ST	

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
CN18	32	40	50	I	ST	Interrupt-on-Change Inputs.
CN19	—	65	80	I	ST	
CN20	—	37	47	I	ST	
CN21	—	38	48	I	ST	
CVREF	23	29	34	O	ANA	Comparator Voltage Reference Output.
EMUC1	15	19	24	I/O	ST	In-Circuit Emulator Clock Input/Output.
EMUD1	16	20	25	I/O	ST	In-Circuit Emulator Data Input/Output.
EMUC2	17	21	26	I/O	ST	In-Circuit Emulator Clock Input/Output.
EMUD2	18	22	27	I/O	ST	In-Circuit Emulator Data Input/Output.
ENVREG	57	71	86	I	ST	Enable for On-Chip Voltage Regulator.
IC1	42	54	68	I	ST	Input Capture Inputs.
IC2	43	55	69	I	ST	
IC3	44	56	70	I	ST	
IC4	45	57	71	I	ST	
IC5	52	64	79	I	ST	
INT0	35	45	55	I	ST	External Interrupt Inputs.
INT1	42	13	18	I	ST	
INT2	43	14	19	I	ST	
INT3	44	52	66	I	ST	
INT4	45	53	67	I	ST	
$\overline{\text{MCLR}}$	7	9	13	I	ST	Master Clear (Device Reset) Input. This line is brought low to cause a Reset.
OC1	46	58	72	O	—	Output Compare/PWM Outputs.
OC2	49	61	76	O	—	
OC3	50	62	77	O	—	
OC4	51	63	78	O	—	
OC5	52	66	81	O	—	
OCFA	17	21	26	I	ST	Output Compare Fault A Input.
OCFB	30	36	44	I	ST	Output Compare Fault B Input.
OSC1	39	49	63	I	ANA	Main Oscillator Input Connection.
OSC2	40	50	64	O	ANA	Main Oscillator Output Connection.
PGC1	15	19	24	I/O	ST	In-Circuit Debugger and ICSP™ Programming Clock.
PGD1	16	20	25	I/O	ST	In-Circuit Debugger and ICSP Programming Data.
PGC2	17	21	26	I/O	ST	In-Circuit Debugger and ICSP™ Programming Clock.
PGD2	18	22	27	I/O	ST	In-Circuit Debugger and ICSP Programming Data.

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
PMA0	30	36	44	I/O	ST/TTL	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	29	35	43	I/O	ST/TTL	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2	8	10	14	O	—	Parallel Master Port Address (Demultiplexed Master modes).
PMA3	6	8	12	O	—	
PMA4	5	7	11	O	—	
PMA5	4	6	10	O	—	
PMA6	16	24	29	O	—	
PMA7	22	23	28	O	—	
PMA8	32	40	50	O	—	
PMA9	31	39	49	O	—	
PMA10	28	34	42	O	—	
PMA11	27	33	41	O	—	
PMA12	24	30	35	O	—	
PMA13	23	29	34	O	—	
PMBE	51	63	78	O	—	Parallel Master Port Byte Enable Strobe.
PMCS1	45	57	71	I/O	ST/TTL	Parallel Master Port Chip Select 1 Strobe/Address bit 14.
PMCS2	44	56	70	O	—	Parallel Master Port Chip Select 2 Strobe/Address bit 15.
PMD0	60	76	93	I/O	ST/TTL	Parallel Master Port Data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes).
PMD1	61	77	94	I/O	ST/TTL	
PMD2	62	78	98	I/O	ST/TTL	
PMD3	63	79	99	I/O	ST/TTL	
PMD4	64	80	100	I/O	ST/TTL	
PMD5	1	1	3	I/O	ST/TTL	
PMD6	2	2	4	I/O	ST/TTL	
PMD7	3	3	5	I/O	ST/TTL	
PMRD	53	67	82	I/O	ST/TTL	Parallel Master Port Read Strobe.
PMWR	52	66	81	I/O	ST/TTL	Parallel Master Port Write Strobe.

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
RA0	—	—	17	I/O	ST	PORTA Digital I/O.
RA1	—	—	38	I/O	ST	
RA2	—	—	58	I/O	ST	
RA3	—	—	59	I/O	ST	
RA4	—	—	60	I/O	ST	
RA5	—	—	61	I/O	ST	
RA6	—	—	91	I/O	ST	
RA7	—	—	92	I/O	ST	
RA9	—	23	28	I/O	ST	
RA10	—	24	29	I/O	ST	
RA14	—	52	66	I/O	ST	
RA15	—	53	67	I/O	ST	
RB0	16	20	25	I/O	ST	PORTB Digital I/O.
RB1	15	19	24	I/O	ST	
RB2	14	18	23	I/O	ST	
RB3	13	17	22	I/O	ST	
RB4	12	16	21	I/O	ST	
RB5	11	15	20	I/O	ST	
RB6	17	21	26	I/O	ST	
RB7	18	22	27	I/O	ST	
RB8	21	27	32	I/O	ST	
RB9	22	28	33	I/O	ST	
RB10	23	29	34	I/O	ST	
RB11	24	30	35	I/O	ST	
RB12	27	33	41	I/O	ST	
RB13	28	34	42	I/O	ST	
RB14	29	35	43	I/O	ST	
RB15	30	36	44	I/O	ST	
RC1	—	4	6	I/O	ST	PORTC Digital I/O.
RC2	—	—	7	I/O	ST	
RC3	—	5	8	I/O	ST	
RC4	—	—	9	I/O	ST	
RC12	39	49	63	I/O	ST	
RC13	47	59	73	I/O	ST	
RC14	48	60	74	I/O	ST	
RC15	40	50	64	I/O	ST	

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
RD0	46	58	72	I/O	ST	PORTD Digital I/O.
RD1	49	61	76	I/O	ST	
RD2	50	62	77	I/O	ST	
RD3	51	63	78	I/O	ST	
RD4	52	66	81	I/O	ST	
RD5	53	67	82	I/O	ST	
RD6	54	68	83	I/O	ST	
RD7	55	69	84	I/O	ST	
RD8	42	54	68	I/O	ST	
RD9	43	55	69	I/O	ST	
RD10	44	56	70	I/O	ST	
RD11	45	57	71	I/O	ST	
RD12	—	64	79	I/O	ST	
RD13	—	65	80	I/O	ST	
RD14	—	37	47	I/O	ST	
RD15	—	38	48	I/O	ST	
RE0	60	76	93	I/O	ST	PORTE Digital I/O.
RE1	61	77	94	I/O	ST	
RE2	62	78	98	I/O	ST	
RE3	63	79	99	I/O	ST	
RE4	64	80	100	I/O	ST	
RE5	1	1	3	I/O	ST	
RE6	2	2	4	I/O	ST	
RE7	3	3	5	I/O	ST	
RE8	—	13	18	I/O	ST	
RE9	—	14	19	I/O	ST	
RF0	58	72	87	I/O	ST	PORTF Digital I/O.
RF1	59	73	88	I/O	ST	
RF2	34	42	52	I/O	ST	
RF3	33	41	51	I/O	ST	
RF4	31	39	49	I/O	ST	
RF5	32	40	50	I/O	ST	
RF6	35	45	55	I/O	ST	
RF7	—	44	54	I/O	ST	
RF8	—	43	53	I/O	ST	
RF12	—	—	40	I/O	ST	
RF13	—	—	39	I/O	ST	

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
RG0	—	75	90	I/O	ST	PORTG Digital I/O.
RG1	—	74	89	I/O	ST	
RG2	37	47	57	I/O	ST	
RG3	36	46	56	I/O	ST	
RG6	4	6	10	I/O	ST	
RG7	5	7	11	I/O	ST	
RG8	6	8	12	I/O	ST	
RG9	8	10	14	I/O	ST	
RG12	—	—	96	I/O	ST	
RG13	—	—	97	I/O	ST	
RG14	—	—	95	I/O	ST	
RG15	—	—	1	I/O	ST	
RTCC	42	54	68	O	—	Real-Time Clock Alarm Output.
SCK1	35	45	55	O	—	SPI1 Serial Clock Output.
SCK2	4	6	10	I/O	ST	SPI2 Serial Clock Output.
SCL1	37	47	57	I/O	I^2C	I2C1 Synchronous Serial Clock Input/Output.
SCL2	32	52	58	I/O	I^2C	I2C2 Synchronous Serial Clock Input/Output.
SDA1	36	46	56	I/O	I^2C	I2C1 Data Input/Output.
SDA2	31	53	59	I/O	I^2C	I2C2 Data Input/Output.
SDI1	34	44	54	I	ST	SPI1 Serial Data Input.
SDI2	5	7	11	I	ST	SPI2 Serial Data Input.
SDO1	33	43	53	O	—	SPI1 Serial Data Output.
SDO2	6	8	12	O	—	SPI2 Serial Data Output.
SOSCI	47	59	73	I	ANA	Secondary Oscillator/Timer1 Clock Input.
SOSCO	48	60	74	O	ANA	Secondary Oscillator/Timer1 Clock Output.
$\overline{SS1}$	14	18	23	I/O	ST	Slave Select Input/Frame Select Output (SPI1).
$\overline{SS2}$	8	10	14	I/O	ST	Slave Select Input/Frame Select Output (SPI2).
T1CK	48	60	74	I	ST	Timer1 Clock.
T2CK	—	4	6	I	ST	Timer2 External Clock Input.
T3CK	—	—	7	I	ST	Timer3 External Clock Input.
T4CK	—	5	8	I	ST	Timer4 External Clock Input.
T5CK	—	—	9	I	ST	Timer5 External Clock Input.
TCK	27	33	38	I	ST	JTAG Test Clock/Programming Clock Input.
TDI	28	34	60	I	ST	JTAG Test Data/Programming Data Input.
TDO	24	14	61	O	—	JTAG Test Data Output.
TMS	23	13	17	I	ST	JTAG Test Mode Select Input.

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

TABLE 1-2: PIC24FJ128GA010 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	64-Pin	80-Pin	100-Pin			
$\overline{\text{U1CTS}}$	43	37	47	I	ST	UART1 Clear-to-Send Input.
$\overline{\text{U1RTS}}$	35	38	48	O	—	UART1 Request-to-Send Output.
U1RX	34	42	52	I	ST	UART1 Receive.
U1TX	33	41	51	O	DIG	UART1 Transmit Output.
$\overline{\text{U2CTS}}$	21	27	40	I	ST	UART2 Clear-to-Send Input.
$\overline{\text{U2RTS}}$	29	35	39	O	—	UART2 Request-to-Send Output.
U2RX	31	39	49	I	ST	UART 2 Receive Input.
U2TX	32	40	50	O	—	UART2 Transmit Output.
VDD	10, 26, 38	12, 32, 48	2, 16, 37, 46, 62	P	—	Positive Supply for Peripheral Digital Logic and I/O Pins.
VDDCAP	56	70	85	P	—	External Filter Capacitor Connection (regulator is enabled).
VDDCORE	56	70	85	P	—	Positive Supply for Microcontroller Core Logic (regulator is disabled).
VREF-	15	23	28	I	ANA	A/D and Comparator Reference Voltage (Low) Input.
VREF+	16	24	29	I	ANA	A/D and Comparator Reference Voltage (High) Input.
VSS	9, 25, 41	11, 31, 51	15, 36, 45, 65, 75	P	—	Ground Reference for Logic and I/O Pins.

Legend: TTL = TTL input buffer, ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

NOTES:

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC24FJ128GA010 family family of 16-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Power Supply Pins"**)
- All AVDD and AVSS pins, regardless of whether or not the analog device features are used
  (see **Section 2.2 "Power Supply Pins"**)
- MCLR pin
  (see **Section 2.3 "Master Clear (MCLR) Pin"**)
- ENVREG/DISVREG and VCAP/VDDCORE pins (PIC24F J devices only)
  (see **Section 2.4 "Voltage Regulator Pins (ENVREG/DISVREG and VCAP/VDDCORE)"**)

These pins must also be connected if they are being used in the end application:

- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSCI and OSCO pins when an external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

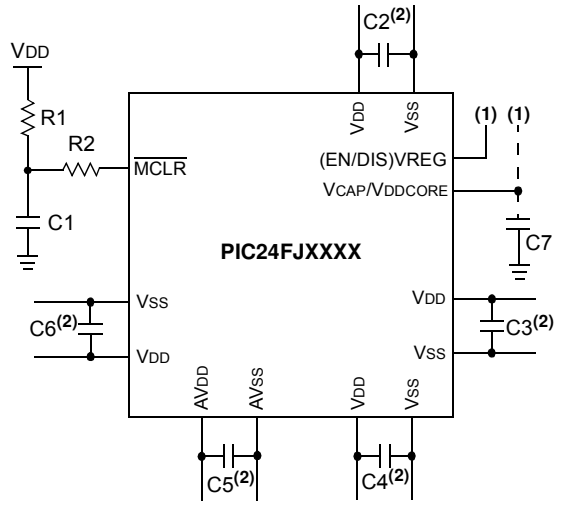
Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for analog modules is implemented

Note:	The AVDD and AVSS pins must always be connected, regardless of whether any of the analog modules are being used.

The minimum mandatory connections are shown in Figure 2-1.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



Key (all values are recommendations):

C1 through C6: 0.1 µF, 20V ceramic

C7: 10 µF, 6.3V or greater, tantalum or ceramic

R1: 10 kΩ

R2: 100Ω to 470Ω

Note 1: See **Section 2.4 "Voltage Regulator Pins (ENVREG/DISVREG and VCAP/VDDCORE)"** for explanation of ENVREG/DISVREG pin connections.

2: The example shown is for a PIC24F device with five VDD/VSS and AVDD/AVSS pairs. Other devices may have more or less pairs; adjust the number of decoupling capacitors appropriately.

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including microcontrollers to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

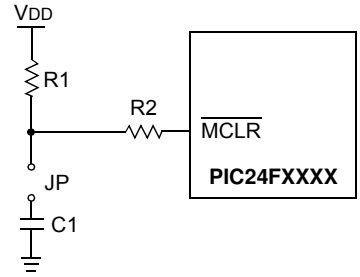
2.3 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides two specific device functions: device Reset, and device programming and debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{MCLR}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the external capacitor, C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2.4 Voltage Regulator Pins (ENVREG/DISVREG and VCAP/VDDCORE)

Note: This section applies only to PIC24F J devices with an on-chip voltage regulator.

The on-chip voltage regulator enable/disable pin (ENVREG or DISVREG, depending on the device family) must always be connected directly to either a supply voltage or to ground. The particular connection is determined by whether or not the regulator is to be used:

- For ENVREG, tie to VDD to enable the regulator, or to ground to disable the regulator
- For DISVREG, tie to ground to enable the regulator or to VDD to disable the regulator

Refer to **Section 24.2 "On-Chip Voltage Regulator"** for details on connecting and using the on-chip regulator.

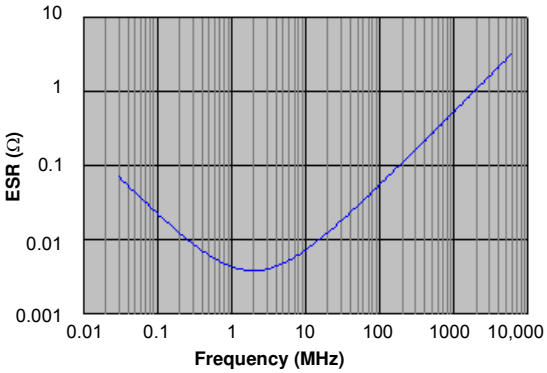
When the regulator is enabled, a low-ESR (< 5Ω) capacitor is required on the VCAP/VDDCORE pin to stabilize the voltage regulator output voltage. The VCAP/VDDCORE pin must not be connected to VDD and must use a capacitor of 10 µF connected to ground. The type can be ceramic or tantalum. Suitable examples of capacitors are shown in Table 2-1. Capacitors with equivalent specification can be used.

Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

The placement of this capacitor should be close to VCAP/VDDCORE. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 27.0 "Electrical Characteristics"** for additional information.

When the regulator is disabled, the VCAP/VDDCORE pin must be tied to a voltage supply at the VDDCORE level. Refer to **Section 27.0 "Electrical Characteristics"** for information on VDD and VDDCORE.

FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP



Note: Typical data measurement at 25°C, 0V DC bias.

TABLE 2-1: SUITABLE CAPACITOR EQUIVALENTS

Make	Part #	Nominal Capacitance	Base Tolerance	Rated Voltage	Temp. Range
TDK	C3216X7R1C106K	10 µF	±10%	16V	-55 to 125ºC
TDK	C3216X5R1C106K	10 µF	±10%	16V	-55 to 85ºC
Panasonic	ECJ-3YX1C106K	10 µF	±10%	16V	-55 to 125ºC
Panasonic	ECJ-4YB1C106K	10 µF	±10%	16V	-55 to 85ºC
Murata	GRM32DR71C106KA01L	10 µF	±10%	16V	-55 to 125ºC
Murata	GRM31CR61C106KC31L	10 µF	±10%	16V	-55 to 85ºC

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

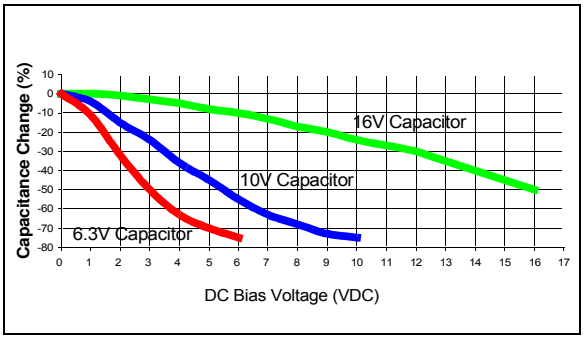
Typical low-cost, 10 μF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R), or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 μF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

Typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 2.5V or 1.8V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming (ICSP) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 26.0 “Development Support”**.

2.6 External Oscillator Pins

Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

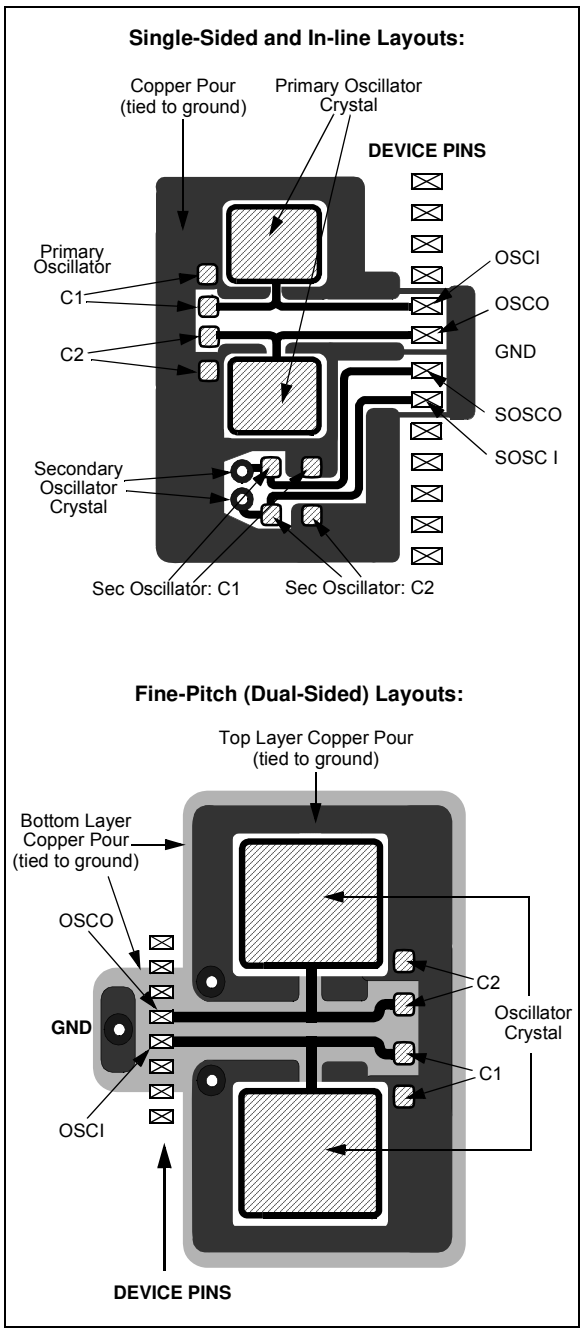
Layout suggestions are shown in Figure 2-5. In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

In planning the application's routing and I/O assignments, ensure that adjacent port pins, and other signals in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times and other similar noise).

For additional information and design guidance on oscillator circuits, please refer to these Microchip Application Notes, available at the corporate web site (www.microchip.com):

- *AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- *AN849, "Basic PICmicro® Oscillator Design"*
- *AN943, "Practical PICmicro® Oscillator Analysis and Design"*
- *AN949, "Making Your Oscillator Work"*

FIGURE 2-5: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Configuration of Analog and Digital Pins During ICSP Operations

If an ICSP compliant emulator is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as “digital” pins. Depending on the particular device, this is done by setting all bits in the ADnPCFG register(s), or clearing all bit in the ANSx registers.

All PIC24F devices will have either one or more ADnPCFG registers or several ANSx registers (one for each port); no device will have both. Refer to **Section 21.0 “10-bit High-Speed A/D Converter”** for more specific information.

The bits in these registers that correspond to the A/D pins that initialized the emulator must not be changed by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must modify the appropriate bits during initialization of the A/D module, as follows:

- For devices with an ADnPCFG register, clear the bits corresponding to the pin(s) to be configured as analog. Do not change any other bits, particularly those corresponding to the PGECx/PGEDx pair, at any time.
- For devices with ANSx registers, set the bits corresponding to the pin(s) to be configured as analog. Do not change any other bits, particularly those corresponding to the PGECx/PGEDx pair, at any time.

When a Microchip debugger/emulator is used as a programmer, the user application firmware must correctly configure the ADnPCFG or ANSx registers. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic '0', which may affect user application functionality.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state. Alternatively, connect a 1 kΩ to 10 kΩ resistor to V_{SS} on unused pins and drive the output to logic low.

3.0 CPU

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. Refer to **Section 2. "CPU"** (DS39703) in the *"PIC24F Family Reference Manual"* for more information.

The PIC24F CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, and a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M instructions of user program memory space. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `REPEAT` instructions, which are interruptible at any point.

PIC24F devices have sixteen 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K word boundary defined by the 8-bit Program Space Visibility Page (PSVPAG) register. The program to data space mapping feature lets any instruction access program space as if it were data space.

The Instruction Set Architecture (ISA) has been significantly enhanced beyond that of the PIC18, but maintains an acceptable level of backward compatibility. All PIC18 instructions and addressing modes are supported either directly or through simple macros. Many of the ISA enhancements have been driven by compiler efficiency needs.

The core supports Inherent (no operand), Relative, Literal, Memory Direct and three groups of addressing modes. All modes support Register Direct and various Register Indirect modes. Each group offers up to 7 addressing modes. Instructions are associated with predefined addressing modes depending upon their functional requirements.

For most instructions, the core is capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing trinary operations (that is, A + B = C) to be executed in a single cycle.

A high-speed, 17-bit by 17-bit multiplier has been included to significantly enhance the core arithmetic capability and throughput. The multiplier supports signed, unsigned and Mixed mode 16-bit by 16-bit or 8-bit by 8-bit integer multiplication. All multiply instructions execute in a single cycle.

The 16-bit ALU has been enhanced with integer divide assist hardware that supports an iterative, non-restoring divide algorithm. It operates in conjunction with the `REPEAT` instruction looping mechanism, and a selection of iterative divide instructions, to support 32-bit (or 16-bit) divided by 16-bit integer signed and unsigned division. All divide operations require 19 cycles to complete but are interruptible at any cycle boundary.

The PIC24F has a vectored exception scheme with up to 8 sources of non-maskable traps and up to 118 interrupt sources. Each interrupt source can be assigned to one of seven priority levels.

A block diagram of the CPU is shown in Figure 3-1.

3.1 Programmer's Model

The programmer's model for the PIC24F is shown in Figure 3-2. All registers in the programmer's model are memory mapped and can be manipulated directly by instructions. A description of each register is provided in Table 3-1. All registers associated with the programmer's model are memory mapped.